

## PATENT ASSIGNMENT COVER SHEET

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT		
<b>CONVEYING PARTY DATA</b>			
	<b>Name</b>	<b>Execution Date</b>	
	ZIYANG GAO	06/08/2017	
	XUNQING SHI	06/08/2017	
	SHI WO CHOW	06/08/2017	
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<b>State/Country:</b>	CHINA		
<b>PROPERTY NUMBERS Total: 1</b>			
	<b>Property Type</b>	<b>Number</b>	
	<b>Application Number:</b>	15619532	
<b>CORRESPONDENCE DATA</b>			
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<b>ATTORNEY DOCKET NUMBER:</b>	A016.029.CIPUS		
<b>NAME OF SUBMITTER:</b>	JACQUELINE C. LUI		
<b>SIGNATURE:</b>	/Jacqueline C. Lui/		
<b>DATE SIGNED:</b>	06/13/2017		
<b>Total Attachments: 3</b>			
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### Assignment by Inventors

THIS ASSIGNMENT, made by

- (1) GAO, Ziyang, residing at 1/F, Photonics Centre, Hong Kong Science Park, Shatin, Hong Kong;
  - (2) SHI, Xunqing, residing at 1/F, Photonics Centre, Hong Kong Science Park, Shatin, Hong Kong; and
  - (3) CHOW, Shi Wo, residing at 1/F, Photonics Centre, Hong Kong Science Park, Shatin, Hong Kong
- (hereinafter referred to as Assignor);

WHEREAS, Assignor have invented certain new and useful improvements in a specification entitled "THREE DIMENSIONAL FULLY MOLDED POWER ELECTRONICS MODULE HAVING A PLURALITY OF SPACERS FOR HIGH POWER APPLICATIONS", set forth in a Patent application for Letters Patent of the United States, filed on even date herewith; and

WHEREAS, Hong Kong Applied Science and Technology Research Institute Company Limited, a limited liability company organized under and pursuant to the laws of Hong Kong S.A.R., China having its principal place of business at 5/F, Photonics Centre, 2 Science Park East Avenue, Hong Kong Science Park, Shatin, Hong Kong, China (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said inventions and said Application for Letters Patent of the United States, and in and to any Letters Patent of the United States to be obtained therefore and thereon.

NOW, THEREFORE, for good and sufficient consideration, the receipt of which is hereby acknowledged, Assignor have sold, assigned, transferred and set over, and by these presents do sell, assign, transfer and set over, unto Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to the above-mentioned inventions and application for Letters Patent, and in and to any and all direct and indirect divisions, continuations and continuations-in-part of said application, and any and all Letters Patent in the United States and all foreign countries which may be granted therefore and thereon, and reissues, reexaminations and extensions of said Letters Patent, and all rights under the International Convention for the Protection of Industrial Property, the same to be held and enjoyed by Assignee, for its own use and benefit and the use and benefit of its successors, legal representatives and assigns, to the full end of the term or terms for which Letters Patent may be granted and/or extended, as fully and entirely as the same would have been held and enjoyed by Assignor, had this sale and assignment not been made.

AND for the same consideration, Assignor hereby represent and warrant to Assignee, its successors, legal representatives and assigns, that, at the time of execution and delivery of these presents, except for any rights, titles and/or interests that have arisen to Assignee under law or that have already been transferred to Assignee, Assignor are the sole and lawful owners of the entire right, title and interest in and to the said inventions and application for Letters Patent above-mentioned, and that the same are unencumbered and that Assignor have good and full right and lawful authority to sell and convey the same in the manner herein set forth.

AND for the same consideration, Assignor hereby covenant and agree to and with Assignee, its successors, legal representatives and assigns, that Assignor will sign all papers and documents, take all

lawful oaths and do all acts necessary or required to be done for the procurement, maintenance, enforcement and defense of any Letters Patent and applications for Letters Patent for said inventions, whenever counsel of Assignee, or counsel of its successors, legal representatives and assigns, shall advise: that any proceeding in connection with said inventions, or said Patent application for Letters Patent, or any proceeding in connection with any Letters Patent or applications for Letters Patent for said inventions in any country, including but not limited to interference proceedings, is lawful and desirable; or, that any division, continuation or continuation-in-part of any application for Letters Patent, or any reissue, reexamination or extension of any Letters Patent, to be obtained thereon, is lawful and desirable.

AND Assignor hereby request the Commissioner of Patent and Trademarks to issue said Letters Patent of the United States to Assignee, as Assignee of said inventions and the Letters Patent to be issued thereon, for the sole use and benefit of Assignee, its successors, legal representatives and assigns.


AND Assignor hereby grant the following individuals the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document:

All practitioners at Customer Number: 56374

AND Assignor acknowledges an obligation of assignment of this invention to Assignee at the time the invention was made.

Signed this on 8 June 2017 in Hong Kong, China

Assignor:



GAO, Ziyang  
1/F, Photonics Centre, Hong Kong Science Park, Shatin,  
Hong Kong

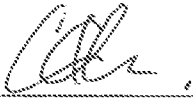
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